# TQP3M9005

#### Applications

• Repeaters

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- Mobile Infrastructure
- LTE / WCDMA
- General Purpose Wireless

**Product Features** 

15.3 dB Gain @ 1.9 GHz

+34 dBm Output IP3

Unconditionally Stable

**General Description** 

50 mA current.

3x3mm QFN package.

temperature variations.

figure.

+22.3 dBm P1dB

0.8 dB Noise Figure @ 1.9 GHz

50 Ohm Cascadable Gain Block

High Input Power Capability

Single Supply, 50 mA Current

<1.5:1 I/O VSWR (>14 dB I/O Return Loss)

The TQP3M9005 is a high linearity low noise gain block amplifier in a low-cost surface-mount package. At 1.9 GHz, the amplifier typically provides 15.3 dB gain, +34 dBm OIP3, and 0.8 dB Noise Figure while only drawing

leadfree/green/RoHS-compliant industry-standard 16-pin

The TQP3M9005 has the benefit of having high linearity while also providing very low noise across a broad range of frequencies. This allows the device to be used in both receive and transmit chains for high performance systems. The amplifier is internally matched using a high performance E-pHEMT process and only requires an external RF choke and blocking/bypass capacitors for operation from a single supply. The internal active bias circuit also enables stable operation over bias and

The TQP3M9005 covers the 0.05 - 4 GHz frequency band and is targeted for wireless infrastructure or other applications requiring high linearity and/or low noise

The device is housed in a

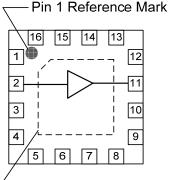
50-4000 MHz





16-pin 3x3 QFN package

#### **Functional Block Diagram**



-Backside Paddle - RF/DC GND

#### **Pin Configuration**

Pin #	Symbol
2	RF Input
11	RF Output / Vdd
All Other Pins	N/C or GND
Backside Paddle	GND

### **Ordering Information**

Part No.	Description	
TQP3M9005	LNA Gain Block	
TQP3M9005-PCB	0.5-4 GHz Evaluation Board	
Standard T/R size = 2500 pieces on a 7" reel.		

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#### **Specifications**

#### Absolute Maximum Ratings

Parameter	Rating
Storage Temperature	-55 to 150 °C
RF Input Power,CW,50 Ω,T=25°C	20 dBm
Device Voltage,Vdd	+7 V

Operation of this device outside the parameter ranges given above may cause permanent damage.

#### **Recommended Operating Conditions**

Parameter	Min	Тур	Max	Unit
Vdd	3	5	5.25	V
Tcase	-40		+85	°C
Tch (for>10 <sup>6</sup> hours MTTF)			190	°C

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

## **Electrical Specifications**

Test conditions unless otherwise noted:  $+25^{\circ}$ C, +5V, 50  $\Omega$  system.

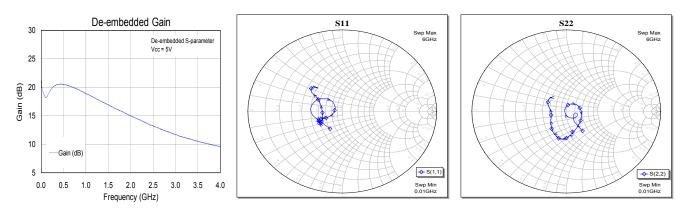
Parameter	Conditions	Min	Typical	Max	Units
Operational Frequency Range		50		4000	MHz
Test Frequency			1900		MHz
Gain		13.9	15.3	16.9	dB
Input Return Loss			12		dB
Output Return Loss			14		dB
Output P1dB			+22.3		dBm
Output IP3	See Note 1.	+30	+34		dBm
Noise Figure			0.8		dB
Supply Voltage, Vdd			+5		V
Current, Idd		35	50	68	mA
Thermal Resistance (junction to case) $\theta_{jc}$			76.8		°C/W

Notes:

1. OIP3 is measured with two tones at an output power of +2 dBm / tone separated by 1 MHz. The suppression on the largest IM3 product is used to calculate the OIP3 using 2:1 rule. 2:1 rule gives relative value with respect to fundamental tone.



#### **Device Characterization Data**



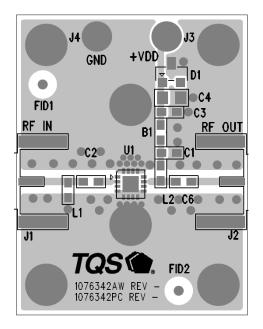
### S-Parameter Data

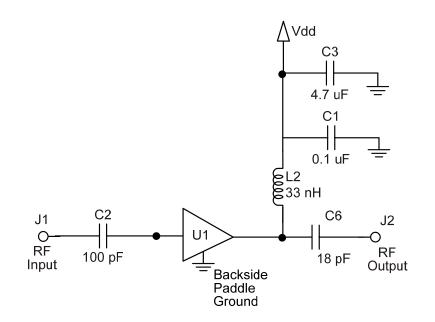
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$\mathbf{V} = \pm 5 \mathbf{V} \mathbf{I}$	= 50  mA,  T = +25	C unmetched 5(	) along avatam	antibrated to	darrian landa
$\mathbf{v}_{dd} = \pm \mathbf{j} \mathbf{v} \cdot \mathbf{I}_{ca}$	$-30 \text{ mA}, 1 - \pm 23$	C. unmalched St	j omn system.	cambrated to	device leads
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Freq (MHz)	S11 (dB)	S11 (ang)	S21 (dB)	S21 (ang)	S12 (dB)	S12 (ang)	S22 (dB)	S22 (ang)
50	-10.60	-165.03	18.97	169.37	-28.21	3.31	-20.93	-16.62
100	-9.49	175.55	18.25	174.21	-28.93	7.02	-18.17	-16.66
200	-10.87	147.24	19.40	177.58	-27.58	15.94	-20.08	-53.04
400	-17.37	131.91	20.53	160.55	-26.03	13.26	-35.69	161.57
800	-19.08	-162.95	19.71	130.50	-25.55	10.38	-18.59	54.50
1000	-16.31	-155.70	18.89	118.70	-25.42	10.64	-17.17	35.91
1200	-14.56	-155.11	18.10	108.64	-25.21	11.47	-16.62	16.88
1500	-13.21	-157.04	16.88	94.87	-24.85	13.11	-15.65	-9.94
1900	-12.17	-158.41	15.32	79.10	-24.31	13.69	-14.06	-43.51
2000	-11.91	-158.36	14.97	75.77	-24.10	13.71	-13.59	-50.29
2200	-11.68	-157.13	14.26	68.76	-23.87	13.48	-12.60	-62.64
2500	-11.30	-155.40	13.24	59.49	-23.35	12.97	-11.28	-75.63
2600	-11.23	-154.34	12.92	56.53	-23.20	12.81	-10.96	-79.40
3000	-11.03	-150.07	11.67	45.14	-22.54	11.37	-9.77	-89.57
3500	-11.47	-147.07	10.53	31.94	-21.61	7.86	-9.39	-100.67
4000	-13.13	-160.94	9.56	16.71	-20.66	1.90	-10.56	-116.49



#### **Application Circuit Configuration**





Notes:

- 1. See PC Board Layout, under Applications information.
- 2. Components shown on the silkscreen but not on the schematic are not used.
- 3. B1 ( $\hat{0} \Omega$  jumper) may be replaced with copper trace in the target application layout.
- 4. All components are of 0603 size unless stated on the schematic.
- 5. C6 and L2 value are critical for linearity performance.

### Bill of Material: TQP3M9005-PCB

Reference Desg.	Value	Description	Manufacturer	Part Number
U1		High Linearity LNA Gain Block	TriQuint	TQP3M9005
C2	100 pF	Cap, Chip, 0603, 50V, NPO, 5%	various	
C6	18 pF	Cap, Chip, 0603, 50V, NPO, 5%	various	
C1	0.1 uF	Cap, Chip, 0603, 16V, X7R, 10%	various	
L2	33 nH	Ind, Chip, 0603, 5%	various	
C3	4.7 uF	Cap, Chip, 0603, 6.3V, X5R, 20%	various	
B1	0 Ω	Res, Chip, 0603, 1/16W, 5%	various	
L1, D1, C4	Do Not Place		various	



#### **Typical Performance TQP3M9005-PCB**

Test conditions unless otherwise noted: +25°C, +5V, 50 mA, 50 Ω system. The data shown below is measured on TQP3M9005-PCB

Frequency	MHz	500	900	1900	2100	2600
Gain	dB	20.6	19.4	15.3	14.5	12.8
Input Return Loss	dB	19	16	12	11	11
Output Return Loss	dB	17	16	14	13	11
Output P1dB	dBm	+22.2	+22.2	+22.3	+22.5	+22.5
OIP3 [1]	dBm	+32	+32.9	+34.0	+33.6	+33.8
Noise Figure [2]	dB	1.0	0.9	0.8	0.85	1.1

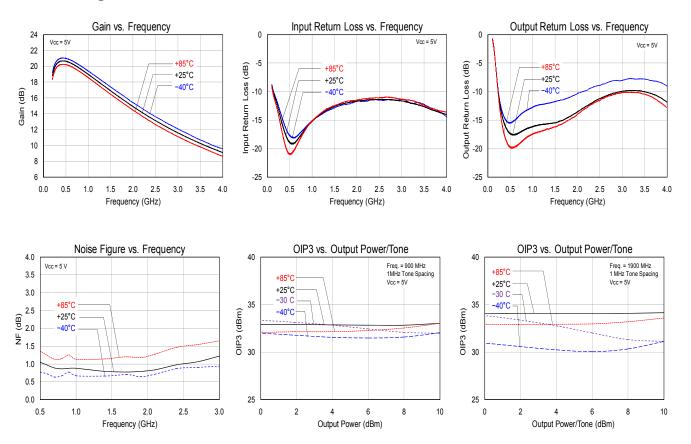
Notes:

1. OIP3 measured with two tones at an output power of +2 dBm / tone separated by 1 MHz. The suppression on the largest IM3 product is used to calculate the OIP3 using 2:1 rule.

2. Noise figure data shown in the table above is measured on evaluation board and corrected for the board loss of 0.11 dB @ 0.5 GHz, board loss of 0.08dB @ 0.9 GHz, board loss of 0.13dB @ 1.9 GHz, board loss of 0.14dB @ 2.1 GHz and board loss of 0.17dB @ 2.6 GHz.

#### **Performance Plots**

Performance plots data is measured using TQP3M9005-PCB. Noise figure plot has been corrected for evaluation board loss of around 0.13dB @ 1.9 GHz.

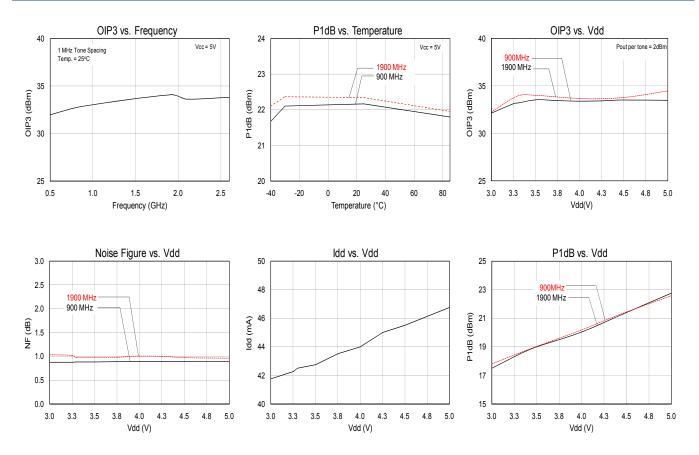


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# TQP3M9005



#### **Performance Plots**

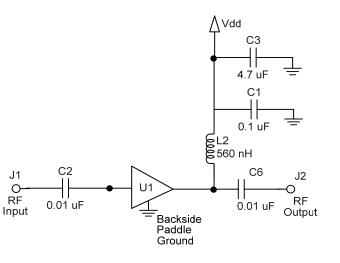




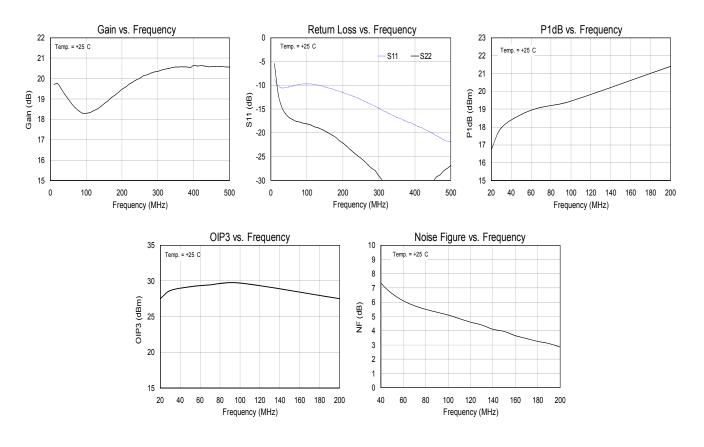
#### TQP3M9005 Low Frequency Performance

Test conditions unless otherwise noted:  $+25^{\circ}$ C, +5V, 50 mA, 50  $\Omega$  system.

Frequency	MHz	50	100	200
Gain	dB	18.9	18.3	19.4
Input Return Loss	dB	10	9.7	11.5
Output Return Loss	dB	16	18	22
Output P1dB	dBm	+18.7	+19.45	+21.4
OIP3	dBm	+29.2	+29.7	+27.5
Noise Figure	dB	6.6	5.1	2.9



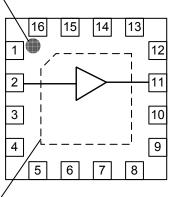
#### Performance Plots



#### Pin Description



— Pin 1 Reference Mark



Backside Paddle - RF/DC GND

Pin	Symbol	Description
2	RF Input	Input, matched to 50 ohms. External DC Block is required.
11	Vdd / RFout	Output, matched to 50 ohms, External DC Block is required and supply voltage.
All other pins	GND	These pins are not connected internally but are recommended to be grounded on the PCB for optimal isolation.
	GND Paddle	Backside Paddle. Multiple vias should be employed to minimize inductance and thermal resistance; see PCB mounting pattern in Mechanical Information section.

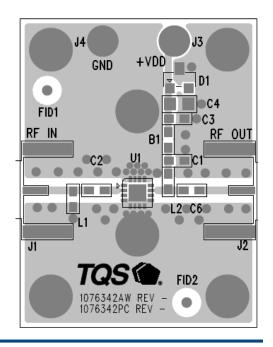
#### **Applications Information**

#### PC Board Layout

Top RF layer is .014" NELCO N4000-13,  $\epsilon_r = 3.9$ , 4 total layers (0.062" thick) for mechanical rigidity. Metal layers are 1-oz copper. 50 ohm Microstrip line details: width = .029", spacing = .035"

The pad pattern shown has been developed and tested for optimized assembly at TriQuint Semiconductor. The PCB land pattern has been developed to accommodate lead and package tolerances. Since surface mount processes vary from company to company, careful process development is recommended.

For further technical information, Refer to www.TriQuint.com

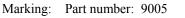


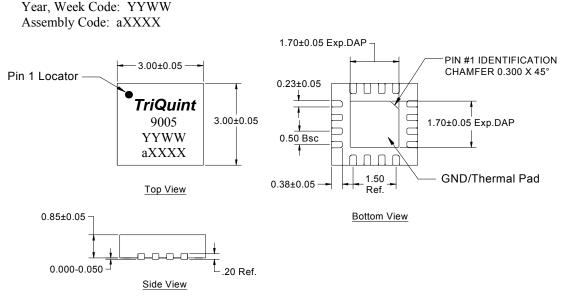
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#### **Mechanical Information**

#### **Package Information and Dimensions**

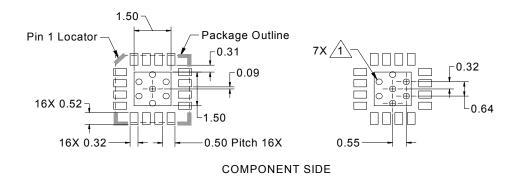




#### NOTES:

1. All dimensions are in millimeters. Angles are in degrees.

#### **PCB Mounting Pattern**



#### Notes:

- 1. All dimensions are in millimeters. Angles are in degrees.
- 2. Use 1 oz. copper minimum for top and bottom layer metal. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance
- 3. Ground/thermal vias are required for the proper operation of this device. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25mm (0.10").
- 4. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.

## TQP3M9005 LNA Gain Block



#### **Product Compliance Information**

#### **ESD** Information



ESD Rating:	Class 1A
Value:	Passes $\ge 250 \text{ V}$ to $< 500 \text{ V}$
Test:	Human Body Model (HBM)
Standard:	JEDEC Standard JESD22-A114

ESD Rating:	Class IV
Value:	Passes $\geq 1000$ V
Test:	Charged Device Model (CDM)
Standard:	JEDEC Standard JESD22-C101

#### **MSL** Rating

Moisture Sensitivity Level 1 at 260°C per IPC/JEDEC J-STD-020.

#### Solderability

Package contact plating: Annealed matte tin.

Compatible with both lead-free (maximum 260°C reflow temperature) and lead (maximum 245°C reflow temperature) soldering processes.

The part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A ( $C_{15}H_{12}Br_40_2$ ) Free
- PFOS Free
- SVHC Free

#### **Contact Information**

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about TriQuint:

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For technical questions and application information:

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